

PCRL75120SQF

Product Preview

1200 V Rectifier Die

Low forward voltage rectifier die for free-wheeling applications.
Ideal for use as a reverse diode in IGBT applications.

Features

- Low V_f
- Soft Fast Reverse Recovery Diode

Typical Applications

- Solar Inverters
- UPS Systems

MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Peak Reverse Voltage, $T_J = 25^\circ\text{C}$	V_{RRM}	1200	V
Max Forward Conduction Current	I_F	(Note 1)	A
Operating Junction Temperature	T_J	-55 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Depending on thermal properties of assembly.

MECHANICAL DATA

Parameter	Symbol	Unit
Die Size	6200 × 3300	μm^2
Die Thickness	121	μm
Wafer Size	150	mm
Total Pad Size (Anode)	5552 × 2652	μm^2
Top Pad metal	3.9 μm AlSi	
Back metal	2 μm AlTiNiAg	
Passivation	1.5 μm HR NIT	
Max possible chips per wafer	610	
Reject Ink dot size	25 mils	
Recommended storage environment: In original container, in dry nitrogen, or temperature of 18–28 $^\circ\text{C}$, 30–65% RH	Type: Sawn wafer on tape. Storage time: <3 months	

ORDERING INFORMATION

Device	Inking?	Shipping
PCRL75120SQF	Yes	Sawn Wafer on Tape



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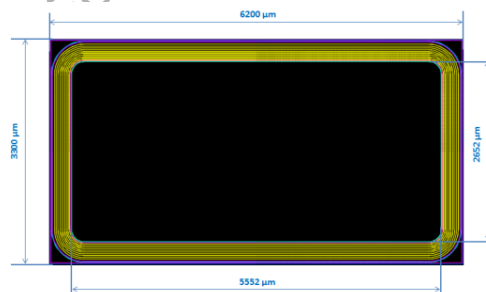
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$V_{RRM} = 1200\text{ V}$
 $I_F = \text{Limited by } T_{J(\text{max})}$

DIODE DIE



DIE OUTLINE



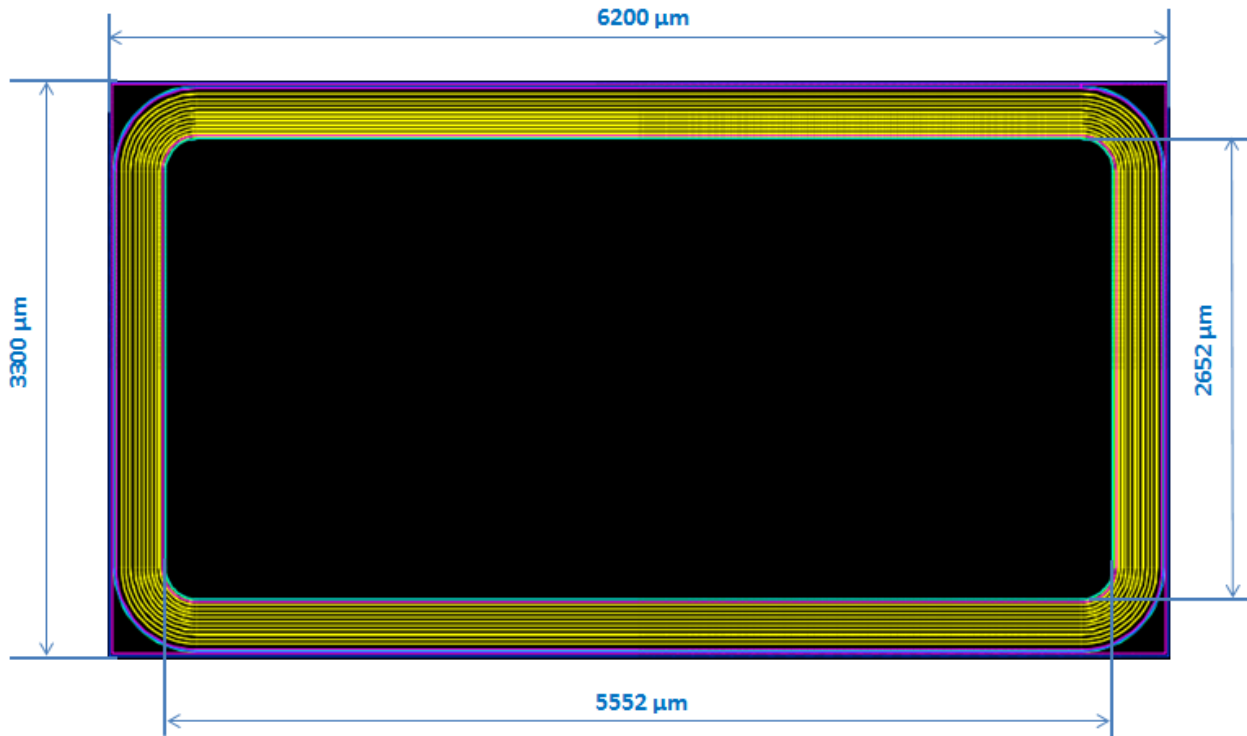
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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Forward Voltage	I _F = 75 A	V _F	–	3.4	4.0	V
Reverse Voltage	I _R = 500 μA	V _R	1200	–	–	V
Reverse Current	V _R = 1200 V	I _R	–	–	400	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



(all dimensions in μm)

Figure 1. Die Layout

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